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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

INFORMATION DISCLOSURE STATEMENT

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APPLICANTS: Nakamura et al. ATTORNEY DOCKET NO: 97,0322  
SERIAL NO.: 08/809,463  
FILED: April 21, 1997  
TITLE: "MULTI-LAYERED STRUCTURE FOR FABRICATING AN OHMIC ELECTRODE AND OHMIC ELECTRODE"

Hon. Assistant Commissioner for Patents,  
Washington, D.C. 20231

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In accordance with the provisions of 37 C.F.R. § 1.56, Applicants request that citation and examination of the following documents be made during the course of examination of the above-referenced application for United States Letters Patent. These references are hereby submitted within three months of the date of the European Search Report for the corresponding European Patent Application and additionally these documents are submitted prior to receipt of a First Official Action for this case, thus no fee is due in accordance with the provisions of 37 C.F.R. §1.97(b)(3).

U.S. DOCUMENTS

<u>REFERENCE</u>	<u>U.S. PATENT NO.</u>	<u>PATENTEE</u>	<u>ISSUE DATE</u>
AA	4,833,042	Waldrop et al.	May 23, 1989
AB	5,089,738	Katz	February 18, 1992
AC	5,027,187	O'Mara, Jr. et al.	June 25, 1991

REFERENCES

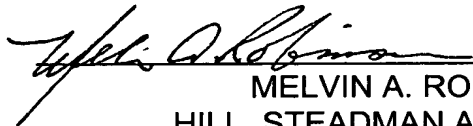
AT IEEE ELECTRON DEVICE LETTERS, vol. EDL6, no. 8, August 1985, pp. 437-438, XP002033693, R.D. Remba et al., "Use of a TiN barrier to improve GaAs FET ohmic contact reliability".

AU JOURNAL OF APPLIED PHYSICS, vol. 68, no. 5, September 1, 1990, pp. 2475-2481, XP000108786, Kim H.-J et al. "Thermally Stable Ohmic Contacts To N-Type GAAS. VIII Sputter-Deposited INAS Contacts".

### **REMARKS**

A copy of the above-identified references together with PTO Form 1449 are submitted herewith. A copy of the Search Report is also enclosed. Applicants submit all claims of the application are patentably distinguishable over the teaching of the above-references, taken alone or in combination. Early consideration of the application is therefore requested. All references are in the English language, thus no further explanation is required.

Submitted by,

 (Reg. 31.870)  
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### **CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231 on October 13, 1997.

  
MELVIN A. ROBINSON